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(71) Applicant: JAPAN SCIENCE & TECHNOLOGY
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(72) Inventor: ESASHI MASAKI

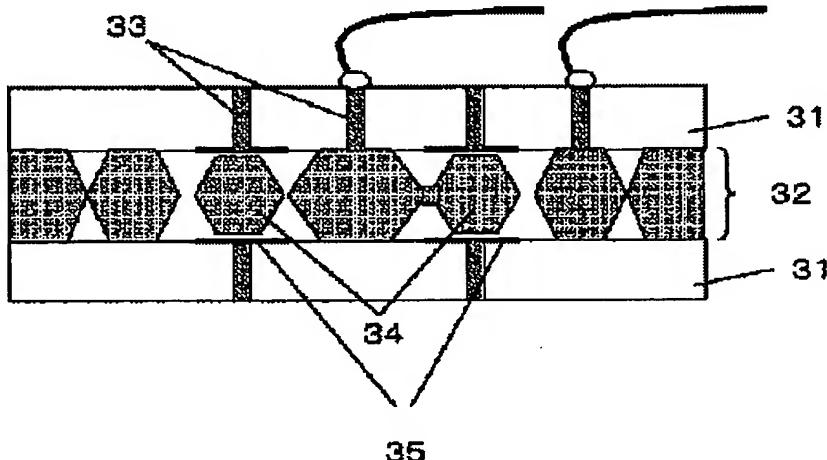
(74) Representative:

(54) SUBSTRATE WITH FIELD-THROUGH AND MANUFACTURING METHOD THEREFOR

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a new substrate material realizing the simplification of a packaging process of a microdevice and furthermore contributing to miniaturization of a micropackage product in the manufacture of 2 micropackage product mounting a micromachine sensor, an actuator and the like.

SOLUTION: Wiring (33) passing through from the reverse side of a substrate (31) to the front side thereof installed within the substrate (31) used as a package for microdevice. The wiring brings about an electric continuity between the front side of the substrate (31) and the reverse side thereof.



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